



FOR IMMEDIATE RELEASE

**Contacts:**

**Aehr Test Systems**

Carl Buck  
V.P. of Marketing  
(510) 623-9400 x381  
[cbuck@aehr.com](mailto:cbuck@aehr.com)

**MKR Group Inc.**

Todd Kehrli or Jim Byers  
Analyst/Investor Contact  
(323) 468-2300  
[aehr@mkr-group.com](mailto:aehr@mkr-group.com)

**AEHR TEST SYSTEMS ANNOUNCES FOLLOW-ON ORDERS FOR FOX™  
CAPACITY ADDITIONS**

**Fremont, CA (June 11, 2014)** – Aehr Test Systems (Nasdaq: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced it has received follow-on orders for increased FOX-15 wafer level burn-in and test system and WaferPak full wafer contactor capacity from a leading communication equipment manufacturer that will increase the manufacturer’s burn-in capacity by 250%.

“We are pleased to receive these orders to significantly expand capacity for this customer. This is another indication of the effectiveness and increasing use of wafer level burn-in for a variety of applications in the communications IC marketplace,” said Mark Allison, vice president of sales at Aehr Test Systems. After purchasing a base configuration, additional capacity can be added at an attractive cost compared to traditional packaged part burn-in systems because in this case, the capacity of a single wafer slot of a FOX-15 system is similar to the capacity of an entire burn-in system for packaged parts.”

“According to IC Insights, the market for communications ICs is growing at over 14% a year, almost twice the growth rate of the IC market as a whole,” commented Carl Buck, vice president of marketing at Aehr Test Systems. “For this particular customer, aging of the IC is required to ensure that critical parameters have stabilized before the IC is assembled into the final product.”

FOX systems, using Aehr Test WaferPak contactors, allow parallel testing of thousands of die on a wafer with only a single touchdown. Aehr Test’s FOX family of products is focused on high reliability test needs and long-duration full wafer burn-in and test of products such as automotive ICs, memories and devices with embedded memories, including microcontrollers and smart card devices. The FOX-1 system offers high-throughput single-touchdown sort testing. The FOX-15 system has a capacity of up to 15 WaferPak single-touchdown full wafer contactors for burn-in and test of state-of-the-art integrated circuits. As each wafer contains thousands of ICs, the throughput and capacity of the systems are quite large and suitable for production as well as reliability qualification applications.

With the increasing popularity of stacked and multi-die packaging, each of the die in the package must be highly reliable in order to ensure the highest possible package part yields and to enable the multi-die package to meet the stringent reliability demands of automotive and enterprise server manufacturers. Aehr Test’s FOX systems provide full wafer contact parallel test and burn-in solutions for the die before they are assembled into the package.

**About Aehr Test Systems**

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, capacity needs and opportunities for Aehr Test products in package and wafer level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX families of test and burn-in systems and the DiePak® carrier. The ABTS system is used in production and qualification testing of packaged parts for both lower-power and higher-power logic as well as all common types of memory devices. The FOX system is a full wafer contact test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit the Company's website at [www.aehr.com](http://www.aehr.com).

### **Safe Harbor Statement**

This press release contains certain forward-looking statements based on current expectations, forecasts and assumptions that involve risks and uncertainties. These statements are based on information available to Aehr Test as of the date hereof and actual results could differ materially from those stated or implied due to risks and uncertainties. These statements typically may be identified by the use of forward-looking words or phrases such as "believe," "expect," "intend," "anticipate," "should," "planned," "estimated," and "potential," among others. Forward-looking statements include statements regarding the expected effect of orders on a customer's burn-in capacity. These risks and uncertainties include, without limitation, acceptance by customers of the FOX and WaferPak contactor technologies, acceptance by customers of the WaferPak contactors shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the Securities and Exchange Commission for a more detailed description of the risks facing our business. Aehr Test disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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